



IJW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

SUGATANI, Shinji, et al.

Group Art Unit: 2814

Serial No.: 10/634,839

Examiner: Howard Weiss

Filed: August 6, 2003

P.T.O. Confirmation No.: 8605

For: MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND
SEMICONDUCTOR CHIP USING SOI SUBSTRATE, FACILITATING
CLEAVING (as amended)

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

July 16, 2004

Sir:

In response to the Office Action dated April 16, 2004, entry of the following amendments and remarks, and reconsideration and further examination, are respectfully requested.

Amendments to the Title begin on page 2 of this paper.

Amendments to the Specification begin on page 3 of this paper.

Remarks/Arguments begin on page 4 of this paper.

U.S. Patent Application Serial No. 10/634,839
Amendment dated July 16, 2004
Reply to OA of April 16, 2004

AMENDMENTS TO THE TITLE:

Amend the title to read as follows:

MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND
SEMICONDUCTOR CHIP USING SOI SUBSTRATE, FACILITATING CLEAVING